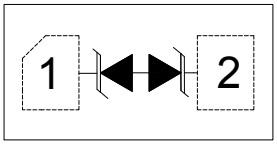
Bi-directional TVS Diode for ESD Protection

FEATURES

- ✧ Protects one bi-directional I/O line
- ✧ Low clamping voltage
- ✧ Low operating voltage:24V
- ✧ Low leakage current
- ✧ Ultra low capacitance: 0.3pF(typ.)
- ✧ RoHS compliant



DFN1006-2L(Bottom view)



Pin Configuration(Top view)

MAIN APPLICATIONS

- ✧ Cell phone handsets and accessories
- ✧ Personal digital assistants (PDA's)
- ✧ Notebooks, desktops, and servers
- ✧ Portable instrumentation
- ✧ Pagers
- ✧ Microprocessor based equipment

PROTECTION SOLUTION TO MEET

- ✧ IEC61000-4-2 (ESD) ±20kV (air), ±15kV (contact)
- ✧ IEC61000-4-4 (EFT) 40A (5/50ns)
- ✧ IEC61000-4-5 (Lightning) 4A (8/20μs)

MECHANICAL CHARACTERISTICS

- ✧ DFN1006-2L package
- ✧ Molding compound flammability rating : UL 94V-0
- ✧ Quantity per reel : 10,000pcs
- ✧ Lead finish : lead free

MARKING CODE

24BU

ORDERING INFORMATION

PART No.	PACKAGE TYPE	QUANTITY(PCS) REEL	DESCIPTION
TESDB24LCDF	DFN1006-2L	10,000	7 inch reel pack

ABSOLUTE MAXIMUM RATING

Symbol	Parameter	Value	Units
V_{ESD}	ESD per IEC 61000-4-2 (Contact) ESD per IEC 61000-4-2 (Air)	±15 ±20	kV
P_{PP}	Peak Pulse Power (8/20μs)	38	W
T_{OPT}	Operating Temperature	-55~125	°C
T_{STG}	Storage Temperature	-55~150	°C

ELECTRICAL CHARACTERISTICS (Tamb=25

Symbol	Parameter	Test Condition	Min	Typ	Max	Units
V_{RWM}	Reverse Working Voltage				24	V
V_{BR}	Reverse Breakdown Voltage	I_T = 1mA	26			V
I_R	Reverse Leakage Current	V_{RWM} = 24V			500	nA
V_C	Clamping Voltage	I_{PP} = 1A, t_p = 8/20μs			38	V
C_J	Junction Capacitance	V_R = 0V, f = 1MHz		0.3	0.5	pF

ELECTRICAL CHARACTERISTICS CURVE

Fig 1 8/20μs Waveform per IEC61000-4-5

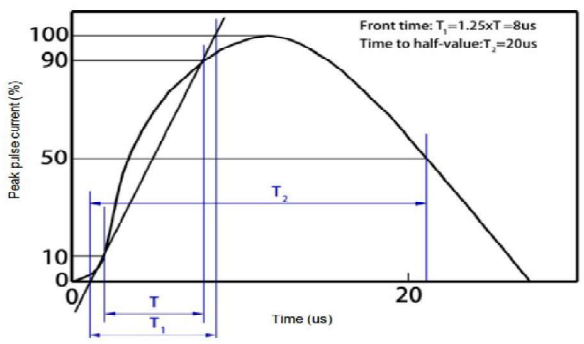


Fig 2 Contact Discharge Current Waveform per IEC 61000-4-2)

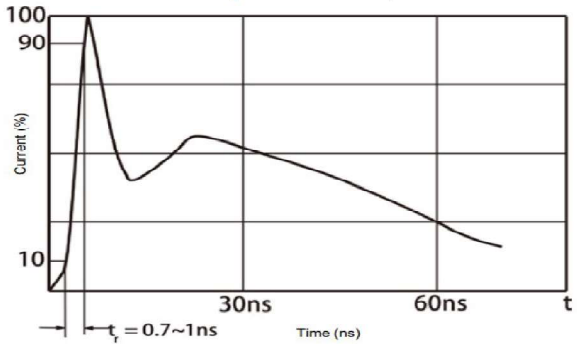


Fig 3 Voltage vs Capacitance

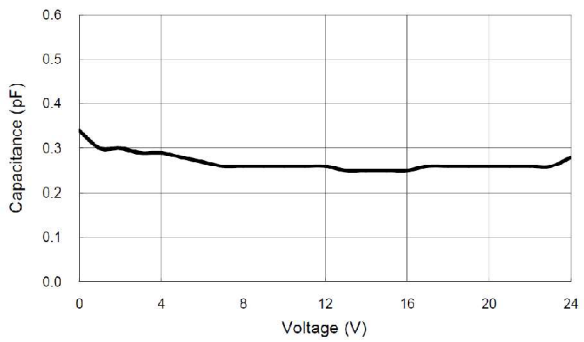
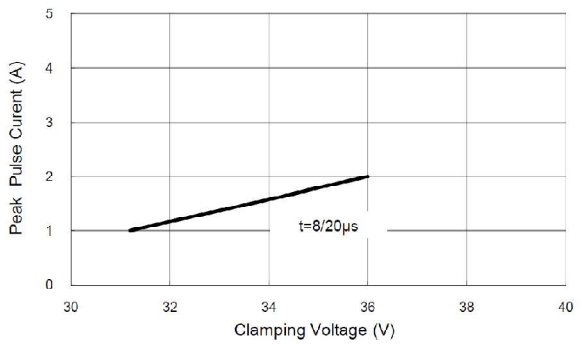
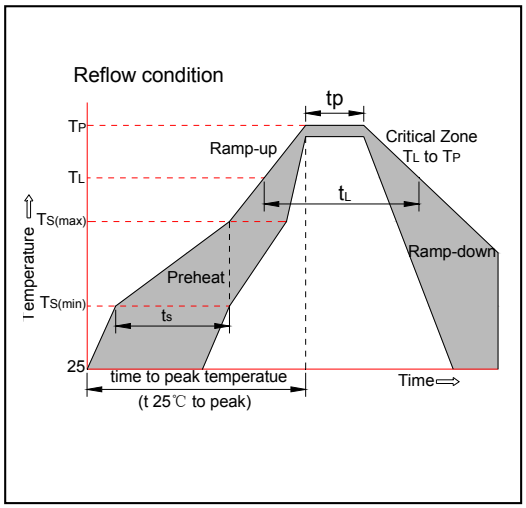


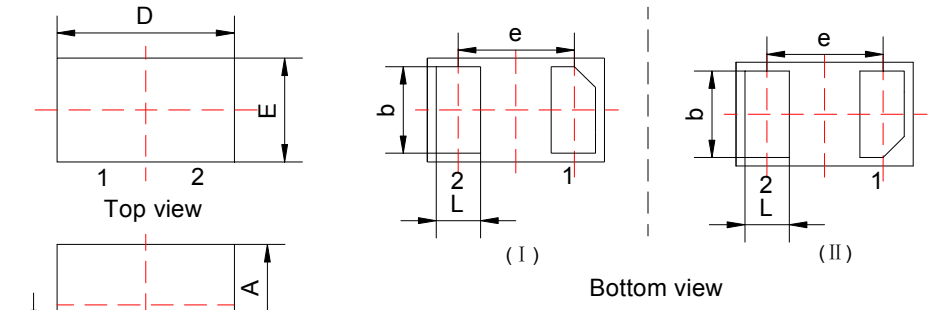
Fig 4 Clamping Voltage vs Peak Pulse Current

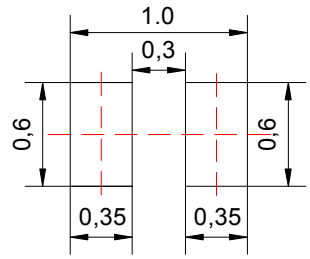


SOLDERING PARAMETERS

Reflow Condition		Pb-Free assembly (see figure at right)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150℃
	-Temperature Max($T_{s(max)}$)	+200℃
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquidus Temp (T_L)to peak)		3℃/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3℃/sec. Max
Reflow	-Temperature(T_L)(Liquidus)	+217℃
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)℃
Time within 5℃of actual Peak Temp (t_p)		20-40secs.
Ramp-down Rate		6℃/sec. Max
Time 25℃ to Peak Temp (T_P)		8 min. Max
Do not exceed		+260℃







Recommended soldering footprint(mm)

Symbol	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.40	0.50	0.55	0.016	0.020	0.022
A1	0.00	0.02	0.05	0.000	0.001	0.002
b	0.45	0.50	0.55	0.018	0.020	0.022
D	0.95	1.00	1.05	0.037	0.039	0.041
e	0.65BSC			0.026BSC		
E	0.55	0.60	0.65	0.022	0.024	0.026
L	0.20	0.25	0.30	0.008	0.010	0.012